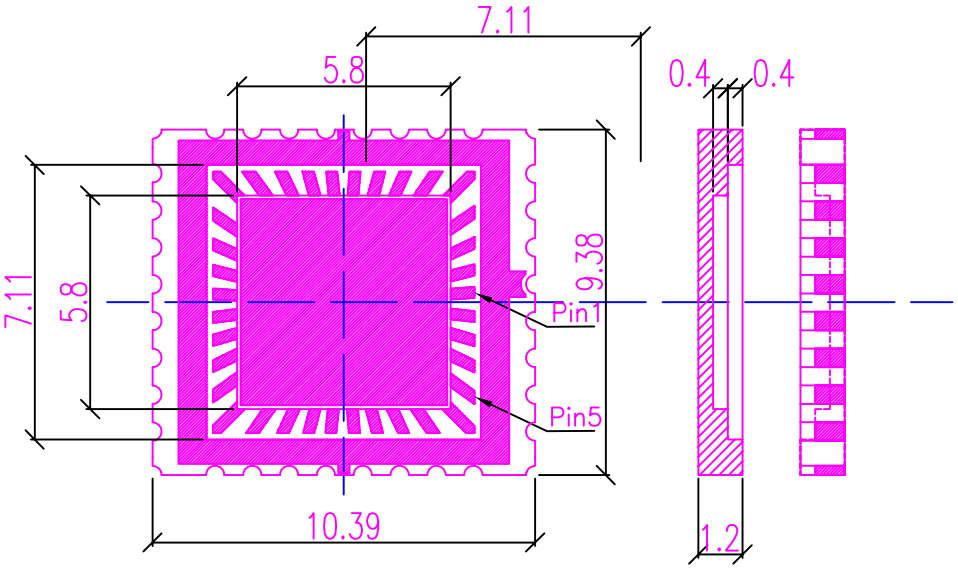
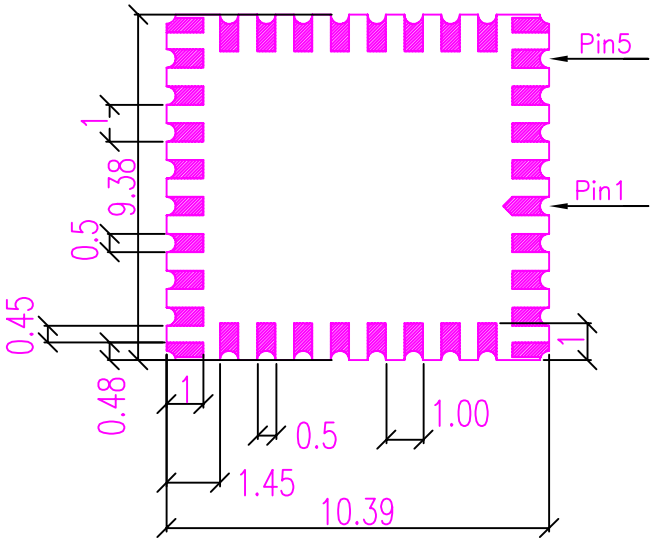
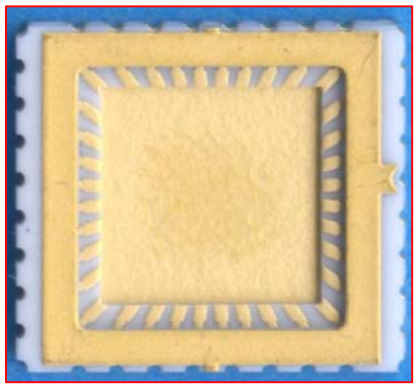
Part Dimensions
36 pin square Ceramic Chip Carrier
MIL-STD-105 D



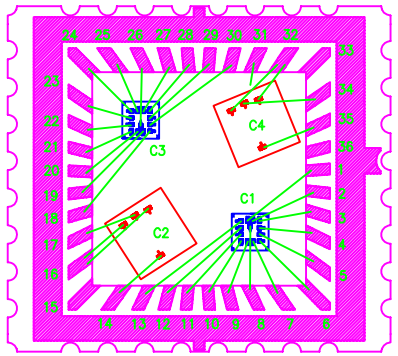




0 1 2 3 4 5 mm

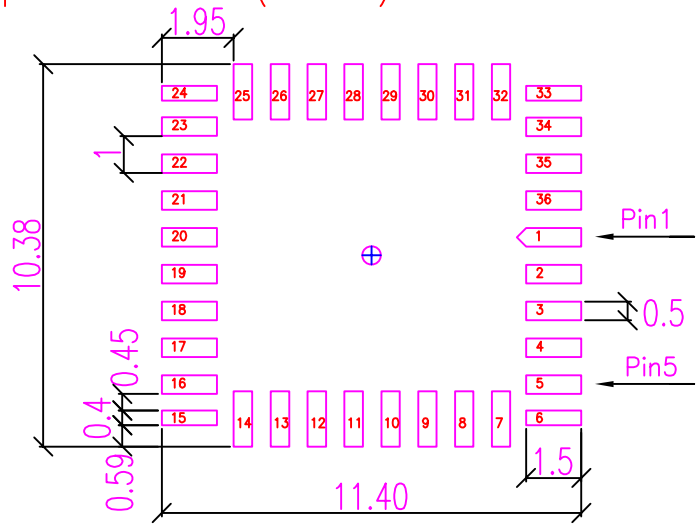
Part bounding (Model 0)

01-C1-D3-K	19-C3-D3-K
02-C1-S2-K	20-C3-S2-K
03-C1-G2-K	21-C3-G2-K
04-C1-D2-K	22-C3-D2-K
05-C1-S1-R	23-C3-S1-R
06-C1-G1-R	24-C3-G1-R
07-C1-D1-R	25-C3-D1-R
08-C1-BULK	26-C3-BULK
09-C1-S4-R	27-C3-S4-R
10-C1-G4-R	28-C3-G4-R
11-C1-D4-R	29-C3-D4-R
12-C1-S3-K	30-C3-S3-K
13-C1-G3-K	31-C2C4-BULK
14-C2-S	32-C4-G
15-FREE	33-FREE
16-C2-G	34-C4-D
17-C2-D	35-C4-S
18-C3-G3-K	36-FREE



C1-REM-TOT501C/504A
C2-LAAS
C3-REM-TOT501C/504A
C4-LAAS

Land pattern LDCC36 (Model 0)



1	Kyocera 36LDCC 9.38 x 10.39 x 1.2 mm3	1	Ceramic	Metallization W or equivalent	
	Specification: AS-1003-A		Kyocera A-473	Lead frame 42 Alloy. Gold plating 99.9% 1.5 um	
QUANT.	DESCRIPTION	POS	MAT.	OBSERVATIONS	REF.CERN
	ENS/ASS		S.ENS/S.ASS		

Chip carrier for REM-LAAS MOSFET dosimeters

RADMON

36LD Chip Carrier

ECHELLE SCALE 10:1

	NOM/NAME	DATE
DES/DRA.	M.Glaser	17/06/2005
CONTROL.		
APPRO.		

PH-DT2-SD

REMPLACE/REPLACES 30/05/2005

IND. 0

0.7TS-PH-0012 0

DIMENSION | <=6 | > 6 | > 30 | > 120 | > 315 | >1000 | >2000
USINAGE MOYEN/MEDIUM MACHINING | ± 0.1 | ± 0.2 | ± 0.3 | ± 0.5 | ± 0.8 | ± 1.2 | ± 2
SOUDURE/WELDED STRUCTURE | ± 0.5 | ± 1 | ± 2 | ± 3 | ± 5 | ± 7 | ± 10

GENERAL TOLERANCES / GENERALES

DESSIN, RUGOSITE, TOLERANCES SELON NORMES ISO
DRAWING, RUGOSITY, TOLERANCES ACCORDING TO ISO STANDARDS

PROJECTION

ORGANISATION EUROPEENNE POUR LA RECHERCHE NUCLEAIRE
EUROPEAN ORGANIZATION FOR NUCLEAR RESEARCH
GENEVE